Advances in Polymeric Materials for Biomedical Applications

Message from the Guest Editors

Dear Colleagues,

This Special Issue is dedicated to recent advances in natural and synthetic polymeric materials with desired physical, chemical, biological, biomechanical and degradation properties to match the various requirements of specific biomedical applications. Discussion of the manufacturing of the advanced polymeric materials and their application in the biomedical field is also welcome.

It is our pleasure to invite you to contribute a manuscript to this Special Issue. Full research papers, short communications, and reviews are all welcome.

Prof. Dr. Iza K. Radecka
Prof. Dr. Marek M. Kowalczuk
Guest Editors

Deadline for manuscript submissions:
closed (31 December 2020)
Editor-in-Chief

Prof. Dr. Maryam Tabrizian
James McGill Professor, Professor of Biomedical Engineering, Professor of Bioengineering, Professor of Experimental Surgery, Department of Biomedical Engineering, Faculty of Medicine/Faculty of Dentistry, Duff Medical Science Building, 3775 University Street, Montreal, QC H3A 2B4, Canada

Message from the Editor-in-Chief

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Contact Us

Materials
MDPI, St. Alban-Anlage 66
4052 Basel, Switzerland

Tel: +41 61 683 77 34
www.mdpi.com
materials@mdpi.com
@Materials_Mdpi